

## Ordering Information (Note 4)

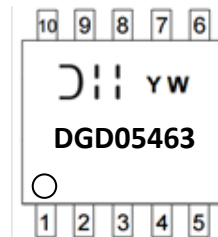
Part Number	Package	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DGD05463FN-7	W-DFN3030-10	DGD05463	7	8	3000
DGD05463M10-13	MSOP-10	DGD05463	13	12	2500

Note: 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

## Marking Information

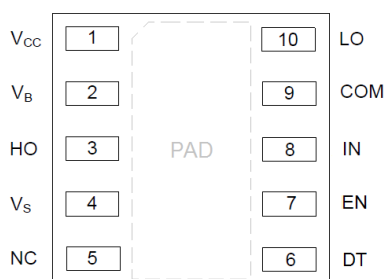


DGD05463 = Product Type Marking Code  
 YY = Year (ex: 21 = 2021)  
 WW = Week (01 to 53)

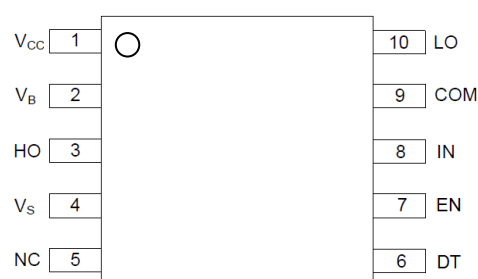


DGD05463 = Manufacturer's Code Marking  
 DGD05463 = Product Type Marking Code  
 Y = Year: 0 ~ 9  
 W = Week: A ~ Z : 1 ~ 26 week  
 a ~ z : 27 ~ 52 week

## Pin Diagrams



Top View: W-DFN3030-10



Top View: MSOP-10

## Pin Descriptions

Pin Number	Pin Name	Function
1	V <sub>CC</sub>	Low-Side and Logic Supply
2	V <sub>B</sub>	High-Side Floating Supply
3	H <sub>O</sub>	High-Side Gate Drive Output
4	V <sub>S</sub>	High-Side Floating Supply Return
5	NC	No Connection (No Internal Connection)
6	DT	Deadtime Control
7	EN	Logic Input Enable, a Logic Low Turns Off Gate Driver
8	IN	Logic Input for High-Side and Low-Side Gate Driver Outputs (H <sub>O</sub> and L <sub>O</sub> ), in Phase with H <sub>O</sub>
9	COM	Low-Side and Logic Return
10	LO	Low-Side Gate Drive Output
PAD	Substrate	Connect to COM on PCB (For W-DFN3030-10 Only)



## Absolute Maximum Ratings (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
High-Side Floating Positive Supply Voltage	$V_B$	-0.3 to +60	V
High-Side Floating Negative Supply Voltage	$V_S$	$V_B - 14$ to $V_B + 0.3$	V
High-Side Floating Output Voltage	$V_{HO}$	$V_S - 0.3$ to $V_B + 0.3$	V
Offset Supply Voltage Transient	$dV_S / dt$	50	V/ns
Logic and Low-Side Fixed Supply Voltage	$V_{CC}$	-0.3 to +14	V
Low-Side Output Voltage	$V_{LO}$	-0.3 to $V_{CC} + 0.3$	V
Logic Input Voltage (IN and EN)	$V_{IN}$	-0.3 to $V_{CC} + 0.3$	V

## Thermal Characteristics – W-DFN3030-10 (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor (Note 5)	$P_D$	0.4	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	64	$^\circ\text{C/W}$
Thermal Resistance, Junction to Case (Note 5)	$R_{\theta JC}$	42	$^\circ\text{C/W}$
Operating Temperature	$T_J$	+150	$^\circ\text{C}$
Lead Temperature (Soldering, 10s)	$T_L$	+300	
Storage Temperature Range	$T_{STG}$	-55 to +150	

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

## Thermal Characteristics – MSOP-10 (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor (Note 6)	$P_D$	0.75	W
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	166	$^\circ\text{C/W}$
Thermal Resistance, Junction to Case (Note 6)	$R_{\theta JC}$	32	$^\circ\text{C/W}$
Operating Temperature	$T_J$	+150	$^\circ\text{C}$
Lead Temperature (Soldering, 10s)	$T_L$	+300	
Storage Temperature Range	$T_{STG}$	-55 to +150	

Note: 6. When mounted on a standard JEDEC 2-layer FR-4 board with minimum recommended pad layout.

## Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
High-Side Floating Supply	$V_B$	$V_S + 4.2$	$V_S + 14$	V
High-Side Floating Supply Offset Voltage	$V_S$	(Note 7)	50 (Note 8)	V
High-Side Floating Output Voltage	$V_{HO}$	$V_S$	$V_B$	V
Logic and Low-Side Fixed Supply Voltage	$V_{CC}$	4.5 (Note 9)	14	V
Low-Side Output Voltage	$V_{LO}$	0	$V_{CC}$	V
Logic Input Voltage (IN and EN)	$V_{IN}$	0	5	V
Ambient Temperature	$T_A$	-40	+125	$^\circ\text{C}$

Notes: 7. Logic operation for  $V_S$  of -5V to +50V.

8. Provided  $V_B$  doesn't exceed absolute maximum rating of 60V.

9. For operation of  $V_{CC} = 4.5\text{V}$  to  $4.9\text{V}$ , an external bootstrap Schottky diode (0.3V  $V_{FD}$ , 1A) is necessary, as shown in Figure 3. For operation  $V_{CC} \geq 4.9\text{V}$ , the external Schottky diode is not required.

## DC Electrical Characteristics (V<sub>CC</sub> = V<sub>BS</sub> = 12V, COM = V<sub>S</sub> = 0V, @ T<sub>A</sub> = +25°C, unless otherwise specified.) (Note 10)

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Logic "1" Input Voltage	V <sub>IH</sub>	2.4	—	—	V	—
Logic "0" Input Voltage	V <sub>IL</sub>	—	—	0.8	V	—
Enable Logic "1" Input Voltage	V <sub>ENIH</sub>	1.5	—	—	V	—
Enable Logic "0" Input Voltage	V <sub>ENIL</sub>	—	—	0.7	V	—
Input Voltage Hysteresis	V <sub>INHYS</sub>	—	0.6	—	V	—
High Level Output Voltage, V <sub>BIAS</sub> - V <sub>O</sub>	V <sub>OH</sub>	—	0.45	0.6	V	I <sub>O+</sub> = 100mA
Low Level Output Voltage, V <sub>O</sub>	V <sub>OL</sub>	—	0.15	0.22	V	I <sub>O-</sub> = 100mA
Offset Supply Leakage Current	I <sub>LK</sub>	—	10	50	μA	V <sub>B</sub> = V <sub>S</sub> = 60V
V <sub>CC</sub> Shutdown Supply Current	I <sub>CCSD</sub>	—	0	1	μA	V <sub>IN</sub> = 0V or 5V, V <sub>EN</sub> = 0V
V <sub>CC</sub> Quiescent Supply Current	I <sub>CCQ</sub>	—	0.28	0.5	mA	V <sub>IN</sub> = 0V or 5V, R <sub>DT</sub> = 100kΩ
V <sub>CC</sub> Operating Supply Current	I <sub>CCOP</sub>	—	7.6	—	mA	f <sub>s</sub> = 500kHz, C <sub>L</sub> = 1000pF
V <sub>BS</sub> Quiescent Supply Current	I <sub>BSQ</sub>	—	32	100	μA	V <sub>IN</sub> = 0V or 5V
V <sub>BS</sub> Operating Supply Current	I <sub>BSOP</sub>	—	7.6	—	mA	f <sub>s</sub> = 500kHz, C <sub>L</sub> = 1000pF
Logic "1" Input Bias Current	I <sub>IN+</sub>	—	25	60	μA	V <sub>IN</sub> = 5V
Logic "0" Input Bias Current	I <sub>IN-</sub>	—	0	1	μA	V <sub>IN</sub> = 0V
V <sub>BS</sub> Supply Undervoltage Positive Going Threshold	V <sub>BSUV+</sub>	3.3	3.8	4.2	V	—
V <sub>BS</sub> Supply Undervoltage Negative Going Threshold	V <sub>BSUV-</sub>	2.9	3.3	3.9	V	—
V <sub>CC</sub> Supply Undervoltage Positive Going Threshold	V <sub>CCUV+</sub>	3.3	3.8	4.2	V	—
V <sub>CC</sub> Supply Undervoltage Negative Going Threshold	V <sub>CCUV-</sub>	2.9	3.3	3.9	V	—
Output High Short-Circuit Pulsed Current	I <sub>O+</sub>	1.0	1.5	—	A	V <sub>O</sub> = 0V, PW ≤ 10μs
Output Low Short-Circuit Pulsed Current	I <sub>O-</sub>	1.9	2.5	—	A	V <sub>O</sub> = 15V, PW ≤ 10μs
Forward Voltage of Bootstrap Diode	V <sub>F1</sub>	—	0.67	—	V	I <sub>F</sub> = 100μA
Forward Voltage of Bootstrap Diode	V <sub>F2</sub>	—	1.7	—	V	I <sub>F</sub> = 100mA

Note: 10. The V<sub>IN</sub> and I<sub>IN</sub> parameters are applicable to the two logic pins: IN and EN. The V<sub>O</sub> and I<sub>O</sub> parameters are applicable to the respective output pins: HO and LO.

## AC Electrical Characteristics (V<sub>CC</sub> = V<sub>BS</sub> = 12V, COM = V<sub>S</sub> = 0V, C<sub>L</sub> = 1000pF, @T<sub>A</sub> = +25°C, unless otherwise specified.)

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Turn-on Propagation Delay, HO & LO	t <sub>ON</sub>	65	96	125	ns	R <sub>DT</sub> = 10kΩ
		350	463	580	ns	R <sub>DT</sub> = 100kΩ
Turn-off Propagation Delay, HO & LO	t <sub>OFF</sub>	—	22	56	ns	—
Turn-on Rise Time	t <sub>r</sub>	—	17	35	ns	—
Turn-off Fall Time	t <sub>f</sub>	—	12	25	ns	—
Delay Matching	t <sub>DM</sub>	—	—	50	ns	—
Deadtime: t <sub>DT</sub> LO-HO & t <sub>DT</sub> HO-LO	t <sub>DT</sub>	40	70	100	ns	R <sub>DT</sub> = 10kΩ
		300	430	560	ns	R <sub>DT</sub> = 100kΩ
Deadtime Matching	t <sub>MDT</sub>	—	—	50	ns	R <sub>DT</sub> = 100kΩ

## Timing Waveforms

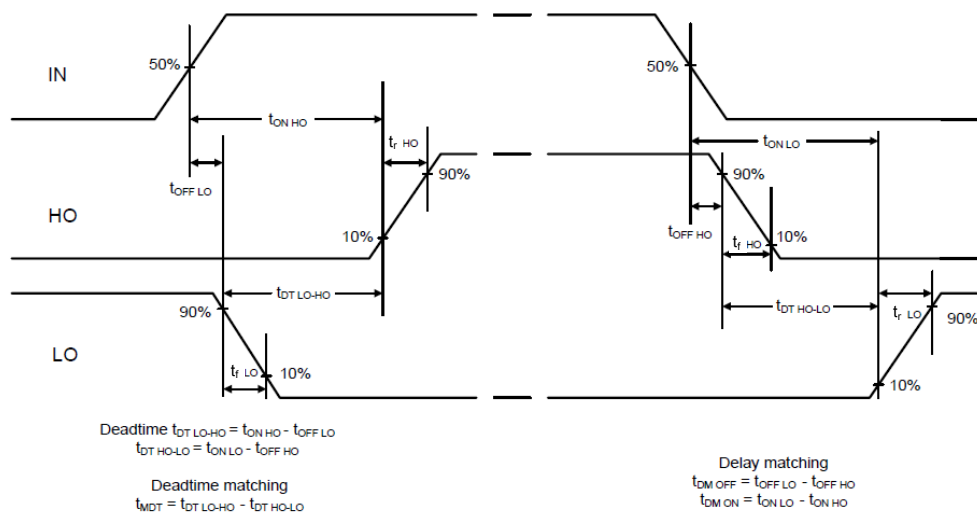


Figure 1. Switching Time Waveform Definitions

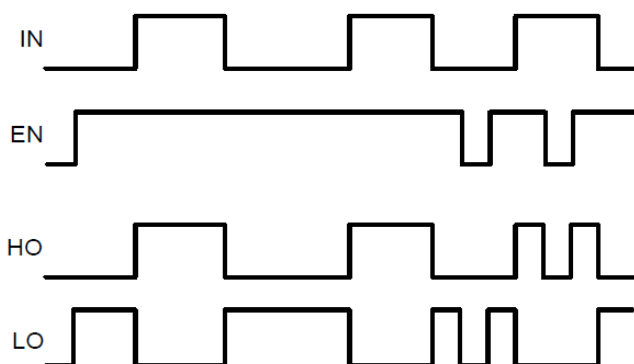


Figure 2. Input / Output Timing Diagram

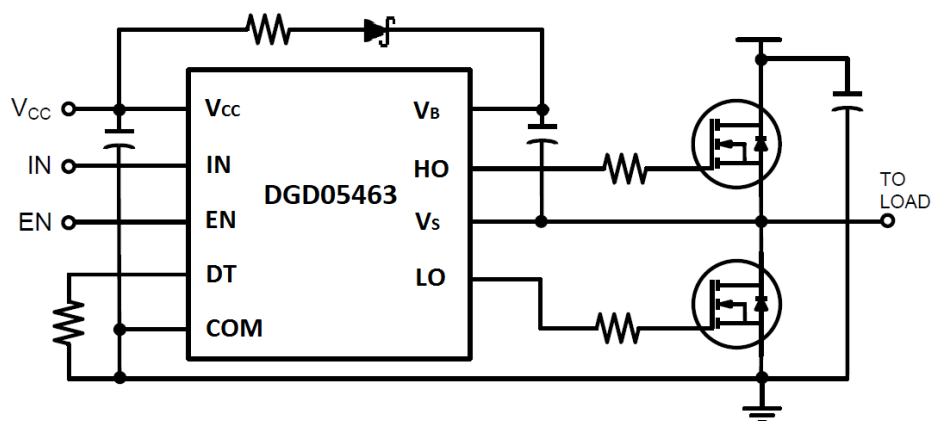


Figure 3. Typical application necessary for  $V_{CC} = 4.5V$  to  $4.9V$  operation. For  $V_{CC} \geq 4.9V$ , the bootstrap Schottky diode (0.3V Voltage drop, 1A) and resistor are not required.

**Typical Performance Characteristics** ( $V_{CC} = 12V$ , @  $T_A = +25^\circ C$ , unless otherwise specified.)

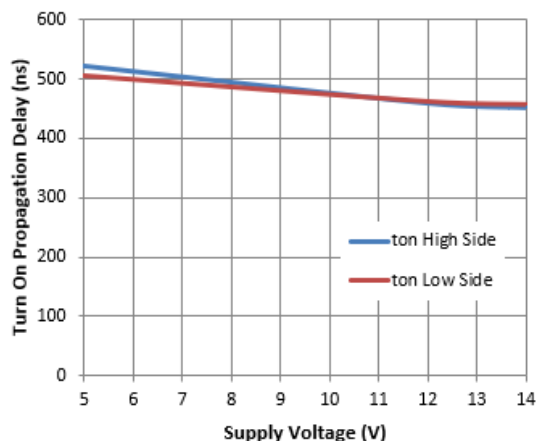


Figure 4. Turn-on Propagation Delay vs. Supply Voltage

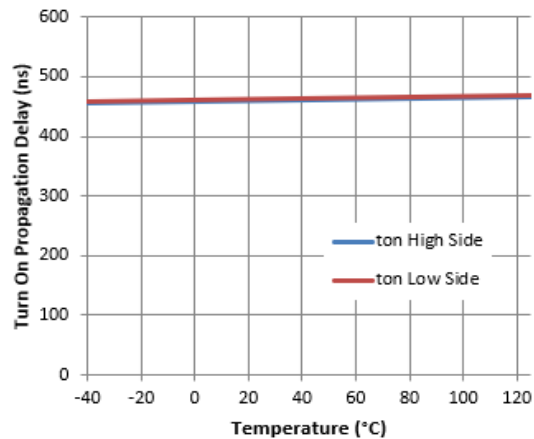


Figure 5. Turn-on Propagation Delay vs. Temperature

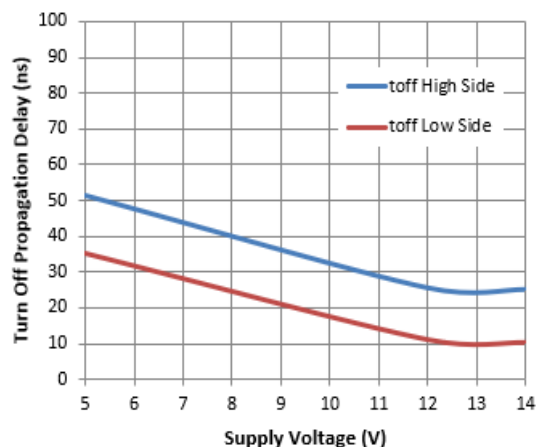


Figure 6. Turn-off Propagation Delay vs. Supply Voltage

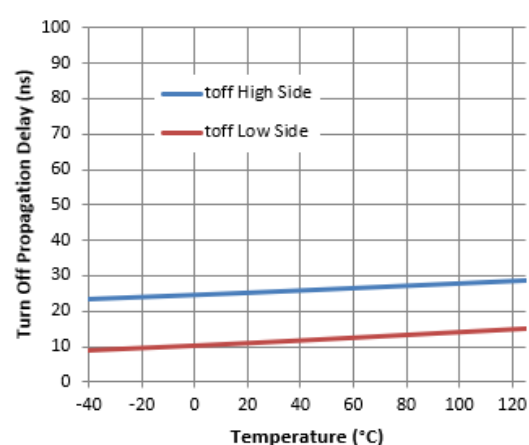


Figure 7. Turn-off Propagation Delay vs. Temperature

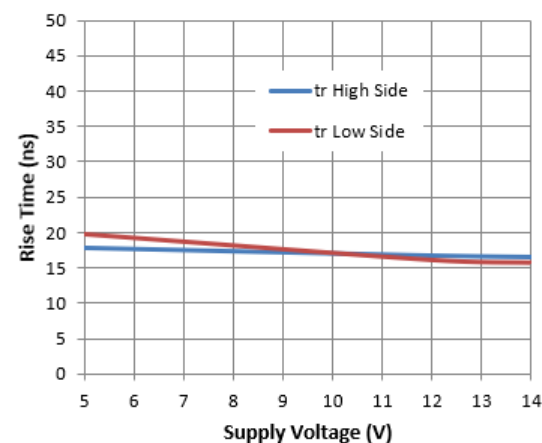


Figure 8. Rise Time vs. Supply Voltage

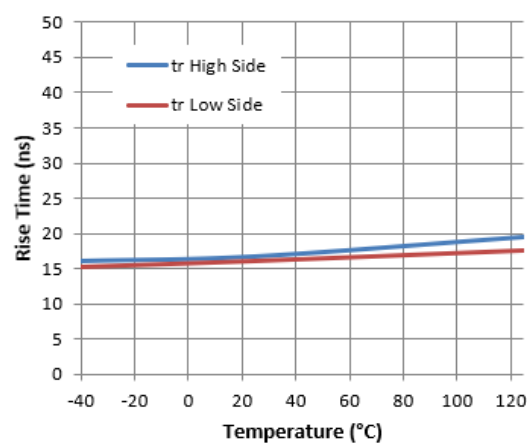


Figure 9. Rise Time vs. Temperature

## Typical Performance Characteristics (continued)

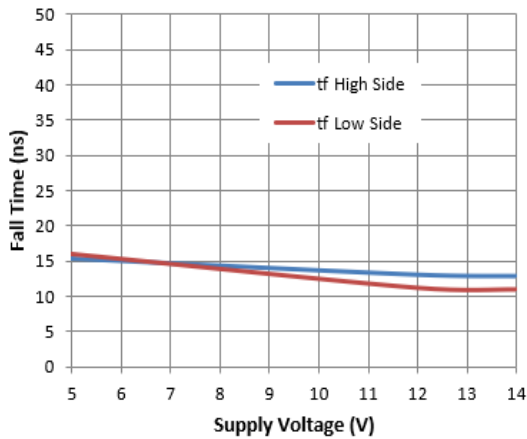


Figure 10. Fall Time vs. Supply Voltage

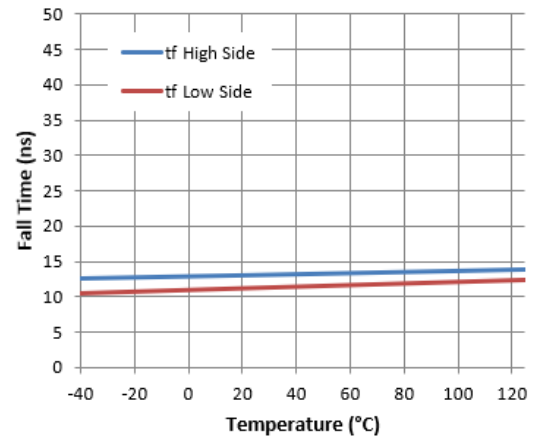


Figure 11. Fall Time vs. Temperature

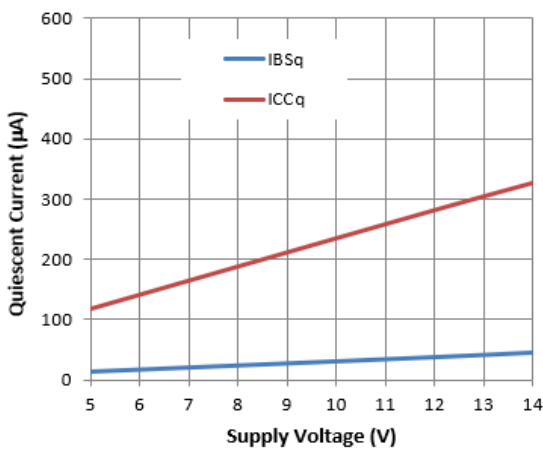


Figure 12. Quiescent Current vs. Supply Voltage

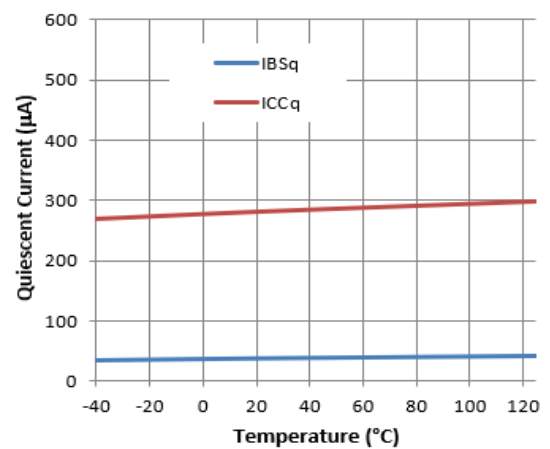


Figure 13. Quiescent Current vs. Temperature

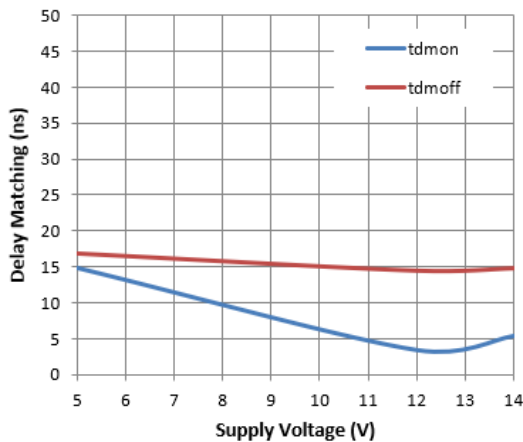


Figure 14. Delay Matching vs. Supply Voltage

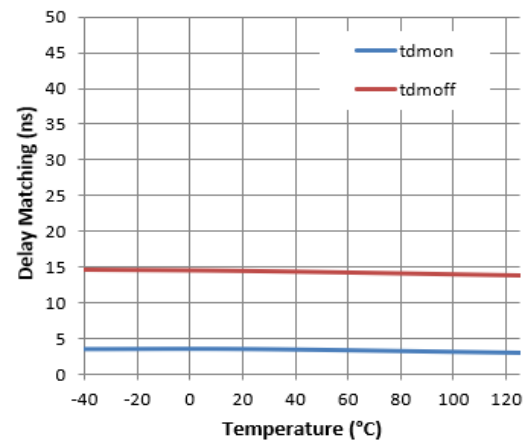


Figure 15. Delay Matching vs. Temperature

## Typical Performance Characteristics (continued)

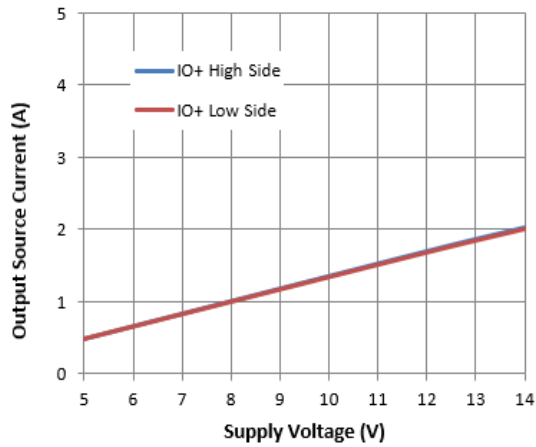


Figure 16. Output Source Current vs. Supply Voltage

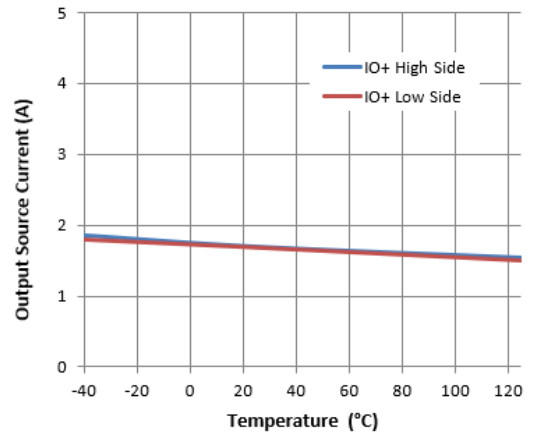


Figure 17. Output Source Current vs. Temperature

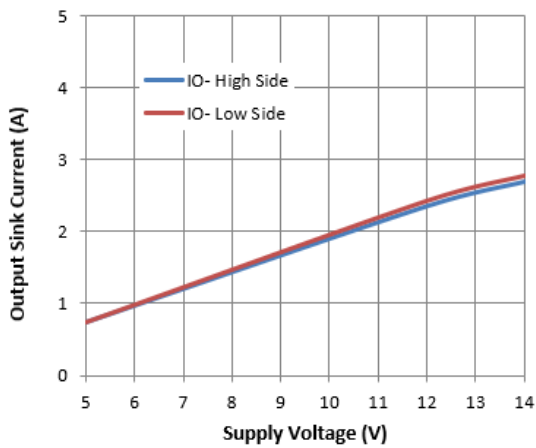


Figure 18. Output Sink Current vs. Supply Voltage

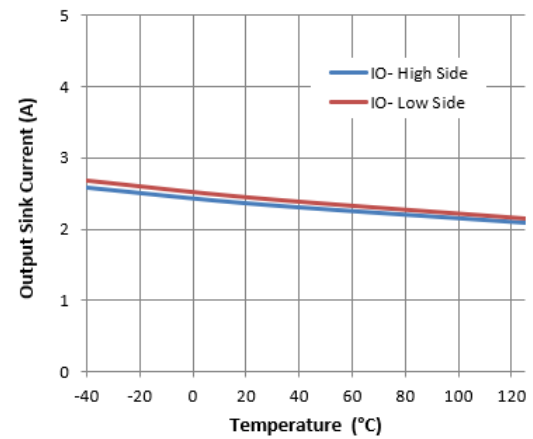


Figure 19. Output Sink Current vs. Temperature

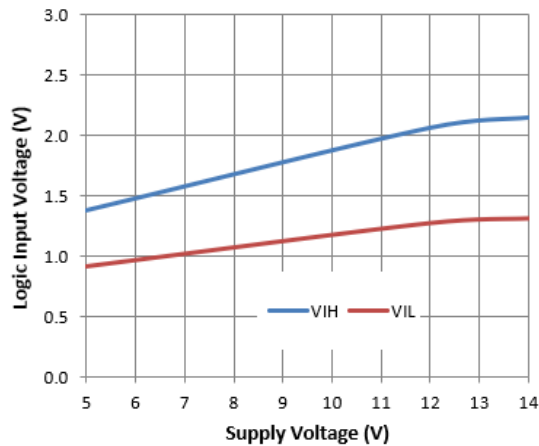


Figure 20. Logic Input Voltage vs. Supply Voltage

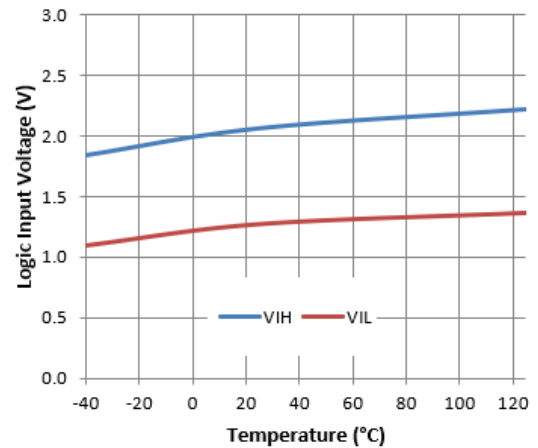


Figure 21. Logic Input Voltage vs. Temperature



## Typical Performance Characteristics (continued)

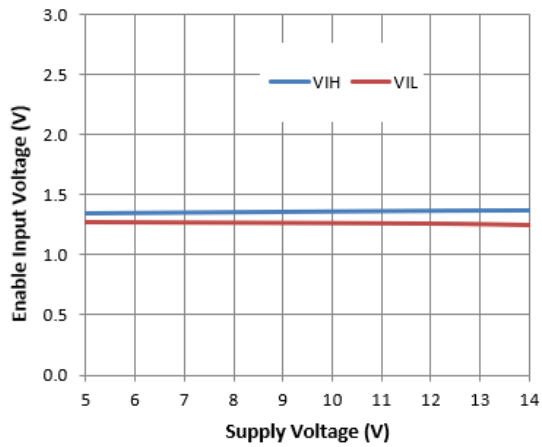


Figure 22. Enable Input Voltage vs. Supply Voltage

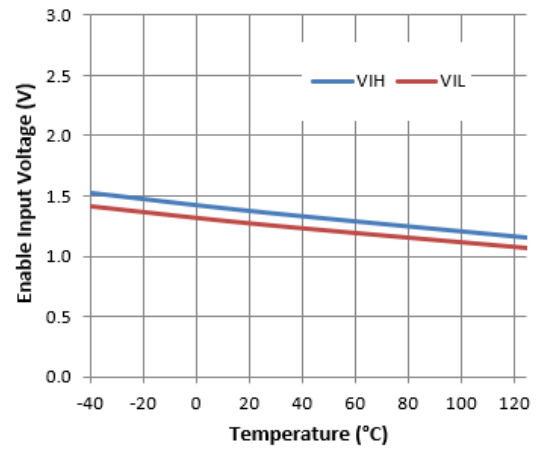


Figure 23. Enable Input Voltage vs. Temperature

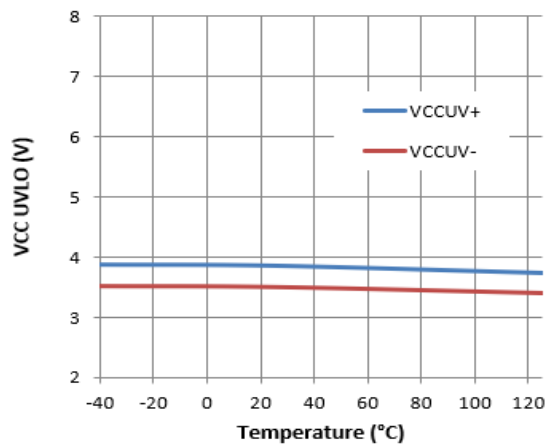


Figure 24. VCC UVLO vs. Temperature

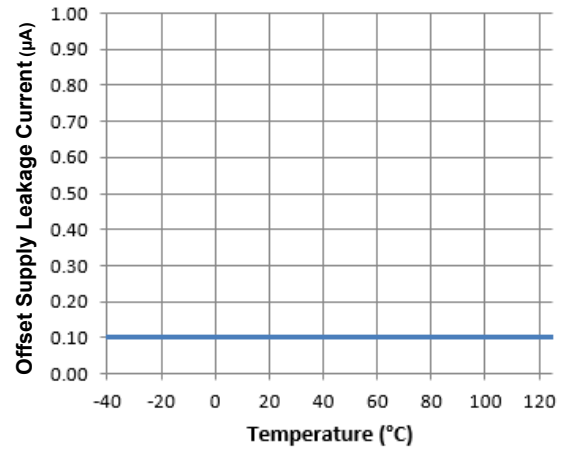


Figure 25. Offset Supply Leakage Current vs. Temperature

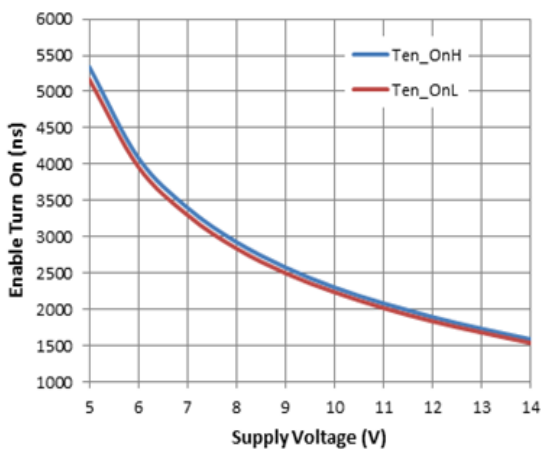


Figure 26. EN to output Ton vs. Supply Voltage

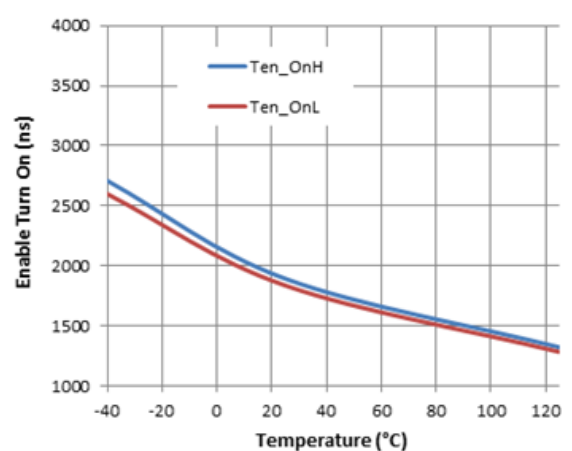


Figure 27. EN to output Ton vs. Temperature

## Typical Performance Characteristics (continued)

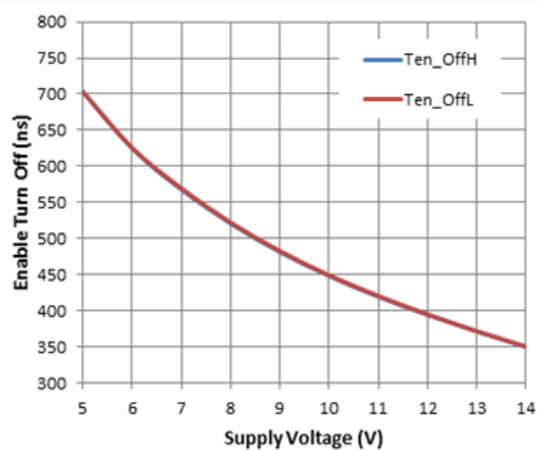


Figure 28. EN to output Toff vs. Supply Voltage

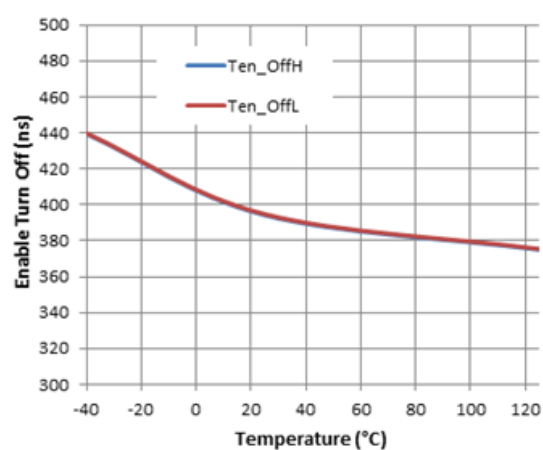
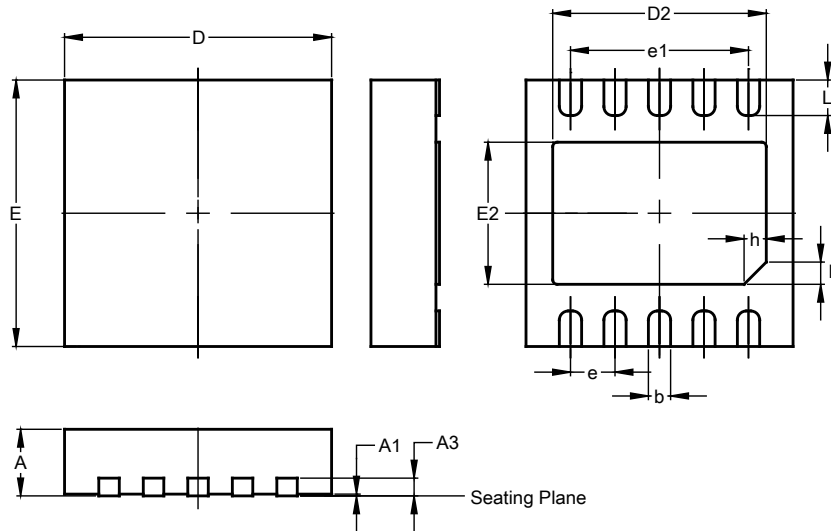


Figure 29. EN to output Toff vs. Temperature

## Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

W-DFN3030-10 (Type TH)

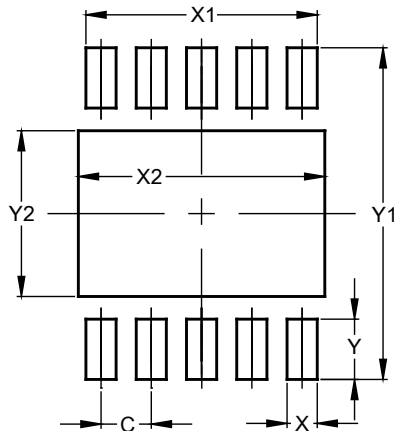


W-DFN3030-10 (Type TH)			
Dim	Min	Max	Typ
A	0.70	0.80	0.75
A1	--	0.05	0.02
A3	0.18	0.25	0.20
b	0.18	0.30	0.25
D	2.90	3.10	3.00
D2	2.40	2.60	2.50
e	0.50BSC		
e1	2.00BSC		
E	2.90	3.10	3.00
E2	1.45	1.65	1.55
h	0.20	0.30	0.25
L	0.30	0.50	0.40
All Dimensions in mm			

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

W-DFN3030-10 (Type TH)

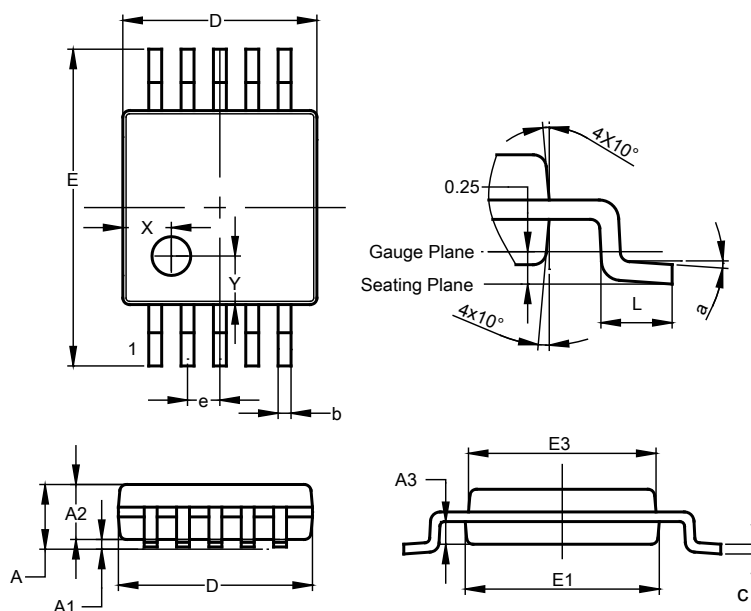


Dimensions	Value (in mm)
C	0.500
X	0.300
X1	2.300
X2	2.600
Y	0.600
Y1	3.300
Y2	1.650

## Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

### MSOP-10

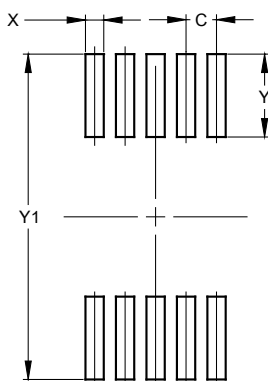


MSOP-10			
Dim	Min	Max	Typ
A	-	1.10	-
A1	0.05	0.15	0.10
A2	0.75	0.95	0.86
A3	0.29	0.49	0.39
b	0.17	0.27	0.20
c	0.08	0.23	0.15
D	2.95	3.05	3.00
e	-	-	0.50
E	4.80	5.00	4.90
E1	2.95	3.05	3.00
E3	2.85	3.05	2.95
L	0.40	0.80	0.60
X	--	--	0.750
Y	--	--	0.750
a	0°	8°	4°
All Dimensions in mm			

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

### MSOP-10



Dimensions	Value (in mm)
C	0.50
X	0.30
Y	1.35
Y1	5.30

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